

WHAT IS CLAIMED IS:

1. A heat-conductive structure comprising a heat-conductive plate, said heat-conductive plate having a base plate, two support members respectively extending
5 upwards from bilateral sides of said base plate for a predetermined breadth and height, a channel formed between said base plate and said two support members, two wing portions extending parallel outwards respectively from said two support members, and a recession formed at a midsection of a bottom side of said base plate; wherein, the midsection of the bottom side of said base plate is relatively thin to have a relatively
10 low thermal resistance, thereby causing rapid heat conduction.

2. The heat-conductive structure as defined in claim 1, wherein said wing portions are positioned higher than said base plate.

15 3. A heat-dissipative structure having the heat-conductive structure as defined in claim 1, said heat-dissipative structure comprising:

a heat-conductive plate having a base plate, two support members extending upwards respectively from bilateral sides of said base plate for a predetermined breadth and height, a channel formed between said base plate and said two support members,
20 two wing portions extending parallel outwards respectively from said two support members, and a recession formed at a midsection of a bottom side of said base plate;

at least one heat pipe disposed in said channel; and

a plurality of fins mounted upright on said heat-conductive plate and said at least one heat pipe, positioned over said channel at bottom sides thereof, and connected
25 to a surface of said heat pipe and top sides of said wing portions.

4. The heat-dissipative structure as defined in claim 3, wherein said heat pipe has at least one end extending outwards and upwards and through said fins.

5 5. The heat-dissipative structure as defined in claim 3 further comprising a top plate mounted on said fins; said heat pipe has at least one end extending outwards and upwards and through said fins.